



## SV0603N5R5G0B

### **Description**

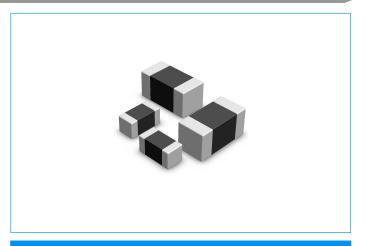
The SV0603N5R5G0B is based on Multilayer fabrication technology. These components are designed to suppress a variety of transient events, including those specified in IEC 61000-4-2 or other standards used for Electromagnetic Compliance (EMC). The SV0603N5R5G0B is typically applied to protect integrated circuits and other components at the circuit board level. It can operate over a wider temperature range than zener diodes.

#### **Features**

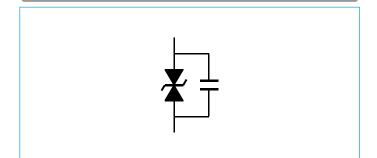
- ◆ SMD type zinc oxide based ceramic chip
- Lead free plating termination provided good solderability characteristic
- Insulator overcoat keeps excellent low and stable leakage current
- Quick response time (<1ns)</li>
- Low clamping voltage
- High transient current capability
- ♦ Meet IEC 61000-4-2 standard
- ◆ Compact size for EIA 0603

#### **Applications**

- Application for Mother Board, Notebook, Cellular Phone, PDA, handheld device, DSC, DV, Scanner, and Set-Top Box...etc.
- Suitable for Push-Button, Power Line and Low Frequency single line over-voltage protect.



#### **Equivalent Circuits**







## SV0603N5R5G0B

## Electrical Characteristics (25±5°C)

Symbol	Minimum	Typical	Maximum	Units
V <sub>RMS</sub>	_	_	4	V
V <sub>DC</sub>	_	_	5.5	V
V <sub>V</sub>	8.0	_	18	V
Vc	_	_	24	V
C <sub>P</sub>	_	270	_	pF
I <sub>max</sub>	_	_	30	А
W <sub>max</sub>	_	_	0.1	W

V<sub>RMS</sub> - Maximum AC operating voltage the varistor can maintain and not exceed 10µA leakage current

V<sub>DC</sub> - Maximum DC operating voltage the varistor can maintain and not exceed 10μA leakage current

 $oldsymbol{V}_V$  - Voltage across the device measure at 1mA DC current. Equivalent to  $V_B$  "breakdown voltage"

Vc - Maximum peak current across the varistor with 8/20µs waveform and 1A pulse current.

**C**<sub>P</sub> - Device capacitance measured with zero volt bias 1Vrms at 1MHz.

I<sub>max</sub> - Maximum peak current which may be applied with 8/20μs waveform without device failure.

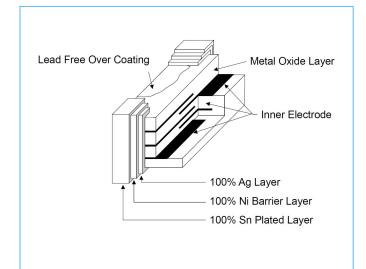
W<sub>max</sub>- Maximum energy which may be dissipated with the 10/1000µs waveform without device failure.

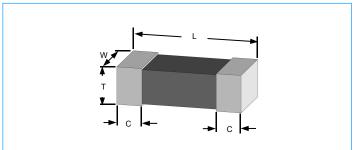




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#### **Construction & Dimensions**





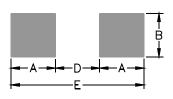
Size EIA (EIAJ)	0603 (1608)		
Symbol	Inches	Millimeters	
L	0.063±0.006	1.60±0.15	
w	0.031±0.004	0.80±0.10	
Т	0.031±0.008	0.80±0.20	
С	0.012±0.008	0.30±0.20	

## Pad Layouts & Precaution for handling of substrate

#### Solder cream in reflow soldering

Refer to the recommendable land pattern as printing mask pattern for solder cream.

(1) Print solder in a thickness of 150 to 200 $\mu m$ 



Size EIA (EIAJ)	0603 (1608)	
Symbol	Inches	Millimeters
Α	0.040	1.02
В	0.030	0.76
D	0.020	0.50
E	0.100	2.54

### Precaution for handling of substrate

Do not exceed to bend the board after soldering thes product extremely. (reference examples)

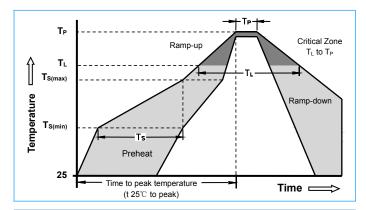
- Mounting place must be as far as possible from the position, which is close to the break line of board or on the line of large holes of board.
- Do not bend extremely the board, in mounting another component. If necessary, use back-up pin (support pin) to prevent from bending extremely.
- Do not break the board by hand. We recommend to use the machine or the jig to break it.





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## **Soldering Parameters**



## **Precaution for soldering**

Note that this product will be easily damaged by rapid heating, rapid cooling or local heating.

Do not give heat shock over 100°C in the process of soldering. We recommend to take preheating and gradual cooling

#### Soldering gun procedure

Note the follows, in case of using solder gun for replacement.

- 1) The tip temperature must be less than 280 for the period within 3 seconds by using soldering gun under 30W
- 2) The soldering gun tip shall not touch this product directly.

### Soldering volume

Note that excess of soldering volume will easily get crack the body of this product.

Reflow Condition Pb-Free assemb		Pb-Free assembly
	-Temperature Min (T <sub>s(min)</sub> )	+150°C
		.0000
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	+200°C
	-Time (min to max) (T <sub>s</sub> )	60 -180 Seconds
Average ramp up rate ( Liquidus Temp $T_L$ ) to peak		3°C/Second Max
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/Second Max
Reflow	- Temperature (T <sub>L</sub> ) (Liquidus)	+217°C
	- Time (min to max) (T <sub>L</sub> )	60 -150 Seconds
Peak Temperature (T <sub>P</sub> ) 260 +0/-5°C		260 +0/-5°C
Time within 5°C of actual peak Temperature (T <sub>P</sub> )		20-40 Seconds
Ramp-down Rate		6°C/Second Max
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes Max

### **General Technical Data**

Operating Temperature		-40 ~ +85°C	
Storage Temperature		-40 ~ +85°C	
Response Time		<1 ns	
Solderability		245±5°C, 3±1sec	
Solder leach resistance		260±5°C, 10±1sec	
Taping Package Storage Condition	Storage Temperature	5 ~ 40°C	
	Relative Humidity	To 65%	
	Storage Time	12 Months max	

#### **Environmental Performance**

Item	Specifications	Test Condition
Bias Humidity	$\triangle V_V / V_V \le \pm 10 \%$	90%RH, 40°C, Working Voltage, 1000 hrs
Thermal Shock	△V <sub>V</sub> / V <sub>V</sub> ≤ ±10 %	-40°C to 85°C, 30 min. cycle, 5 cycles
Full Load Voltage	△V <sub>V</sub> / V <sub>V</sub> ≤ ±10 %	Working Voltage, 85°C,1000 hrs

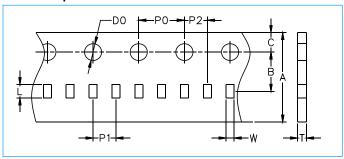




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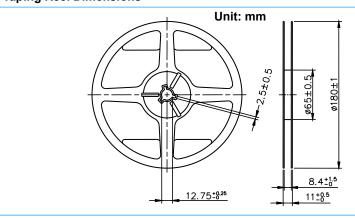
# **Packaging Information**

### **Carrier Tape Dimensions**



Size EIA (EIAJ)	0603 (1608)	
Symbol	Inches	Millimeters
Α	0.315±0.012	8.00±0.30
В	0.138±0.002	3.50±0.05
С	0.069±0.002	1.75±0.10
D0	0.061±0.002	1.55±0.05
P0	0.157±0.004	4.00±0.10
P1	0.079±0.002	4.00±0.10
P2	0.079±0.002	2.00±0.05
W	0.041±0.006	1.05±0.15
L	0.075±0.006	1.90±0.15
Т	0.037±0.002	0.95±0.05

### **Taping Reel Dimensions**



### **Taping Specifications**

There Shall be the portion having no product in both the head and the end of taping, and there shall be the cover tape in the heat of taping.

## Quantity of products in the taping package

SIZE EIA	0603
(EIAJ)	(1608)
Standard Packing Quantity (PCS / reel)	4,000

#### The contents of a box:

0603 Series: 6 reels / inner box